



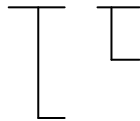
Build in EQ Function 8W Class- F Audio Amplifier With Boost Converter Integrated

General Description

The LPA2163 is a Build in EQ Function 8W, class-F audio amplifier with boost converter integrated. It offers low THD+N, allowing it to achieve high-quality Power Supply sound reproduction. The new filterless architecture allows the device to drive the speaker directly requiring no low-pass output filters, thus to save the system cost and PCB area. With high performance inductor and diode , the boost converter can offer 2A output current for load. It can provide up to 6.5V stable DC voltage for amplifier so that it can display 5.7W output at 10% THD with a 4Ω load. When it provides 5.0V DC voltage, it can provide 3.4W output at 10% THD with a 4Ω load. The LPA2163 also can work at class-AB mode which make LPA2163 could apply to device with radio receiver. The other character of LPA2163 contact OCP、 OTP and high noise suppression for FR signal. The LPA2163 is available in ESOP-16.

Order Information

LPA2163 □ □ □



F: Pb-Free

Package Type

SP: ESOP-16

Applications

- ✧ Portable Bluetooth Speaker
- ✧ Cellular and Smart mobile phone
- ✧ Square Speaker

Features

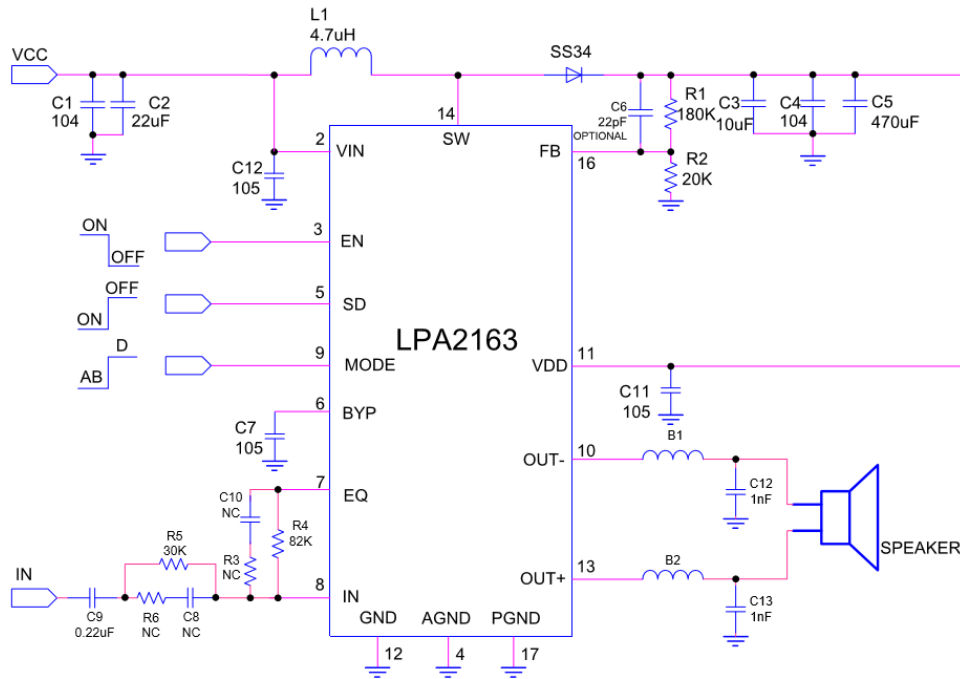
- ◆ Build in EQ Function
- ◆ Integrated boost converter
- ◆ Shut-down current:<3uA
- ◆ Output voltage Up to 5.0V/2.0A
- ◆ Internal Compensation
- ◆ 500KHz fixed frequency switching for amplifier work at class_D mode and 1.2MHz for step up converter
- ◆ POUT at 10% THD+N , VIN=3.7V for boost converter RL=4Ω , POUT=4.8W , boost to 6.0V for amplifier RL=2Ω , POUT=8W , boost to 6.0V for amplifier
- ◆ POUT at 1% THD+N , VIN=3.7V for boost converter RL=4Ω , POUT=3.8W , boost to 6.0V for amplifier RL=4Ω , POUT=6W , boost to 6.0V for amplifier
- ◆ Filterless, Low Quiescent Current and Low EMI
- ◆ Excellent POP&CLICK rejection
- ◆ Amplifier Efficiency up to 84%
- ◆ Excellent POP&CLICK rejection
- ◆ Short Circuit Protection, OCP, OTP
- ◆ Few External Components to Save the Space and cost
- ◆ Free LC filter digital modulation, direct-drive speakers
- ◆ Pb-Free Package

Marking Information

Device	Marking	Package	Shipping
LPA2163SPF	LPS LPA2163 YWX	ESOP-16	2.5K/REEL
Y: Y is year code. W: W is week code. X: X is series number.			



Typical Application Circuit



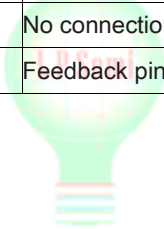
Pin Configuration

Package Type	Pin Configurations
ESOP-16	



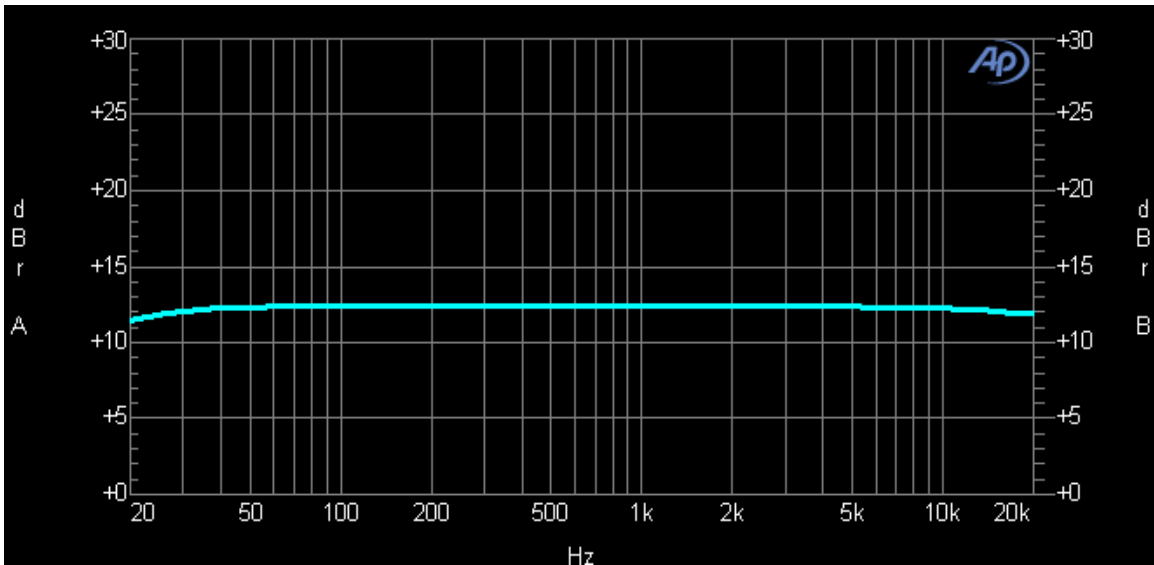
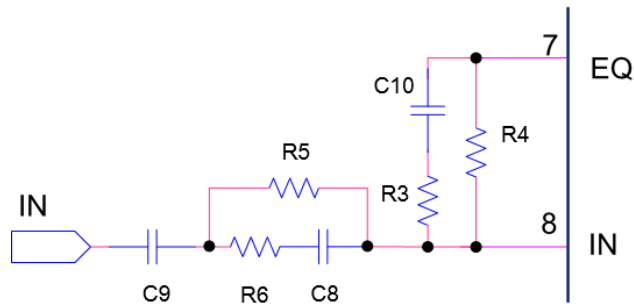
Functional Pin Description

Pin	PIN No.	DESCRIPTION
PGND	1,17	Power ground pin.
VIN	2	Power supply for boost convertor.
EN	3	Enable pin for boost convertor. Active high.
AGND	4	Analog power ground for boost convertor.
SD	5	Amplifier shutdown pin. Active high.
BYP	6	Bypass pin. Connect a 1uF capacitor to ground.
EQ	7	EQ pin of amplifier. With resistor (R3) and capacitor (C10) in series between IN and VEQ, the high frequencies
IN	8	Input of amplifier. With resistor (R6) and capacitor(C8) in series between IN and signal, the low frequencies
MODE	9	Class_AB and class_D mode switch pin. Choise class_D mode with high voltage.
OUT-	10	Negative output of amplifier.
VDD	11	Power supply for amplifier.
GND	12	Ground for amplifier.
OUT+	13	Positive output of amplifier.
SW	14	Switch pin for boost convertor.
NC	15	No connection.
FB	16	Feedback pin.

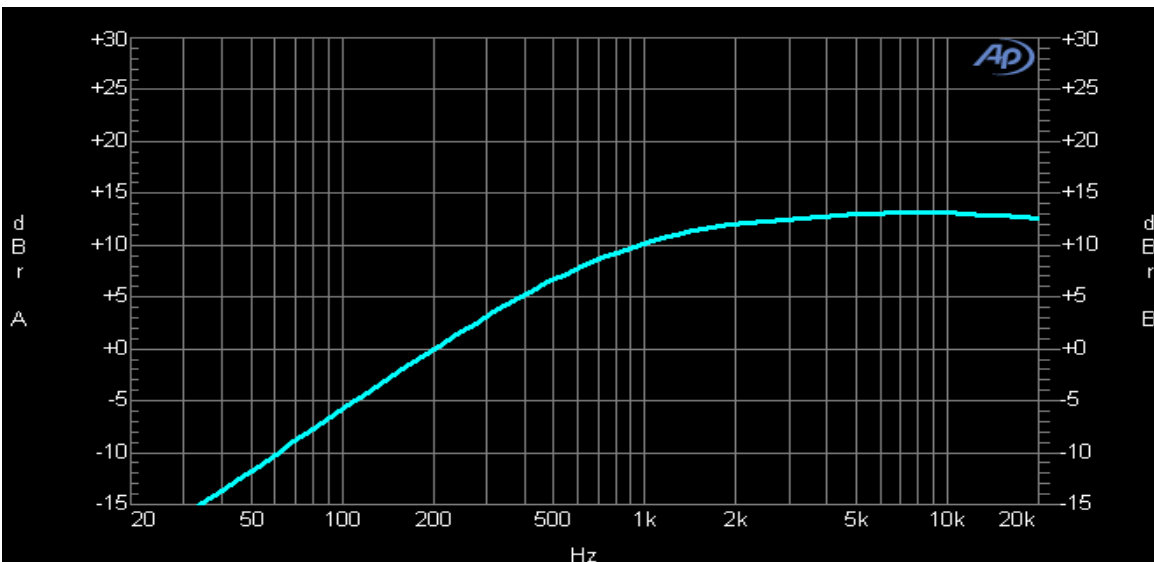




Classical Application 1: Low Restraint



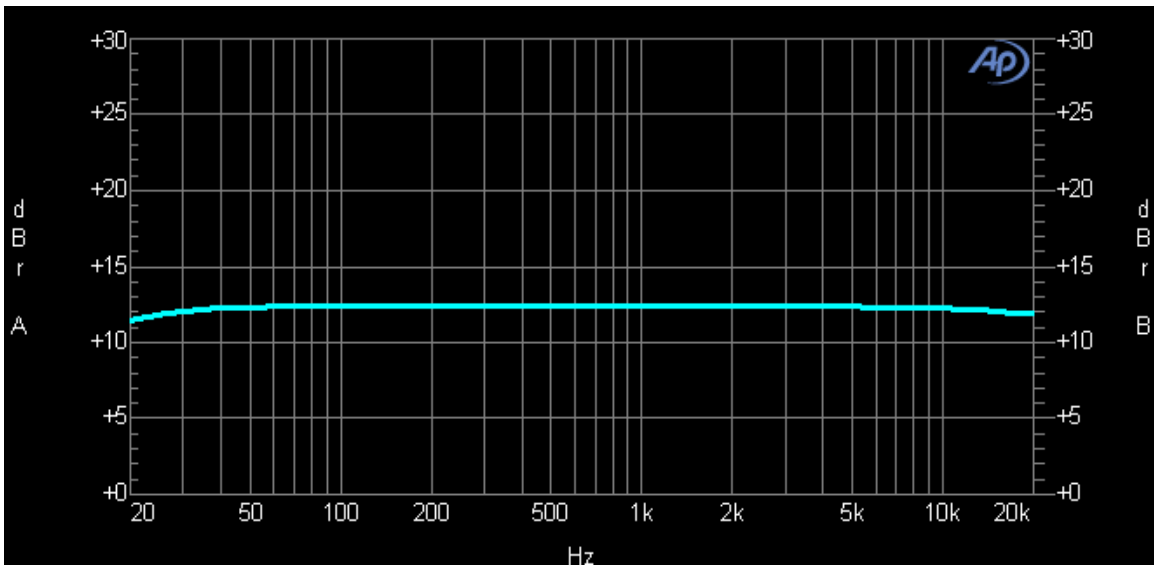
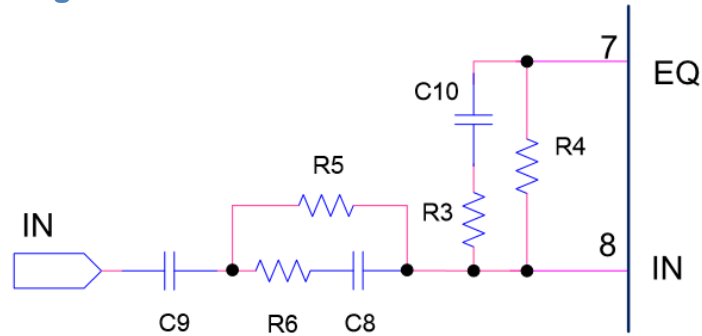
C9=0.22uF,R6=NC,C8=NC,R5=18kΩ,C10=NC,R3=NC,R4=33kΩ



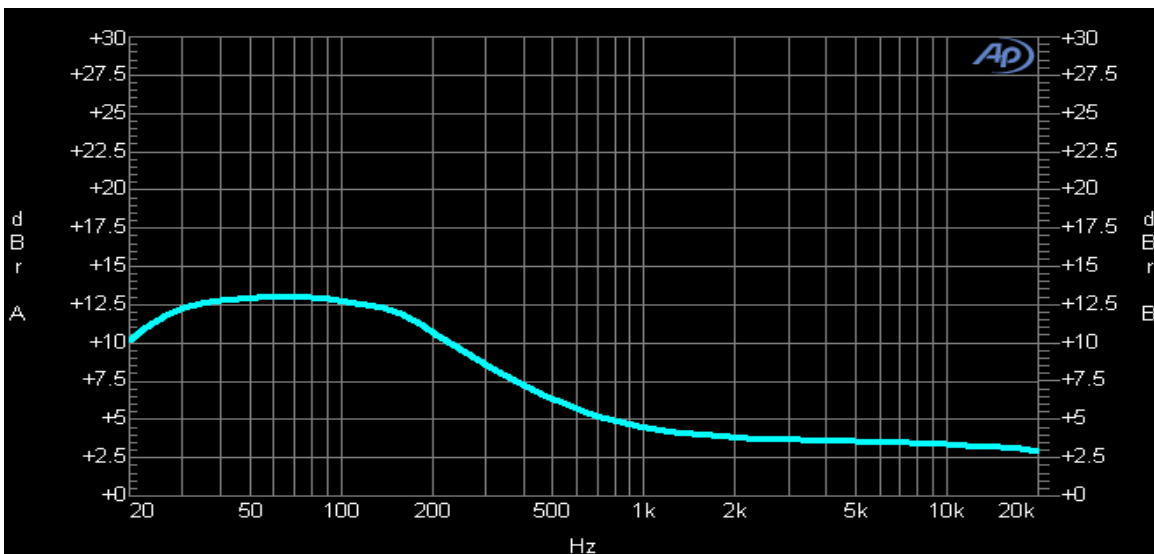
C9=0.1uF,R6=20kΩ,C8=10nF,R5=18kΩ,C10=NC,R3=NC,R4=47kΩ



Classical Application 2: High Restraint



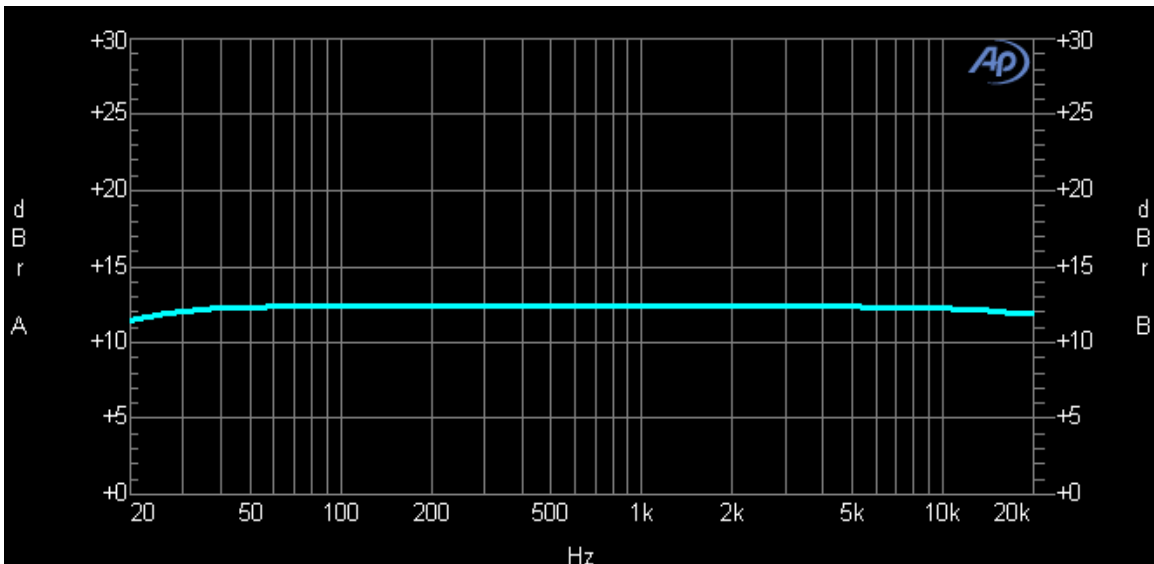
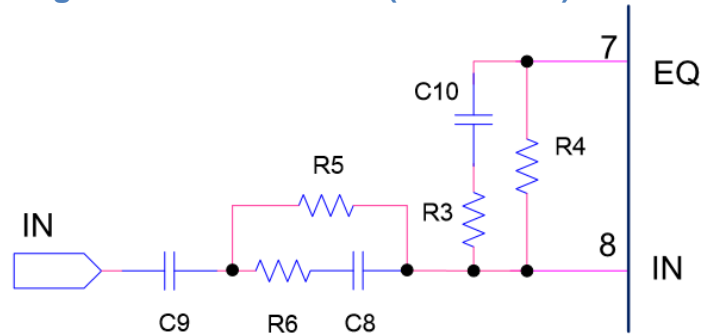
C9=0.22uF,R6=NC,C8=NC,R5=18kΩ,C10=NC,R3=NC,R4=33kΩ



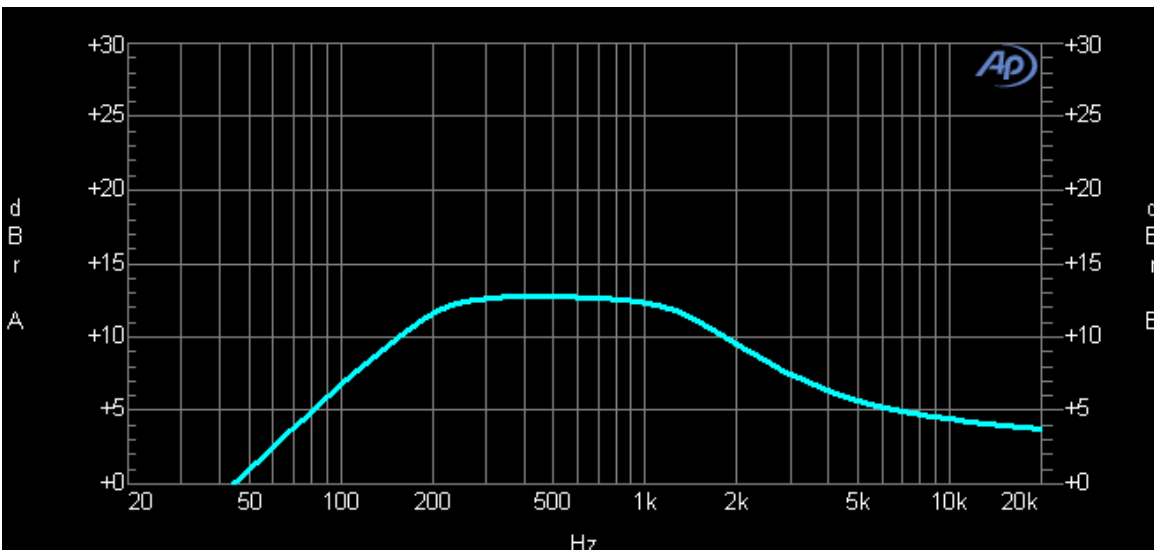
C9=1uF,R6=NC,C8=NC,R5=10kΩ,C10=33nf,R3=10KΩ,R4=47KΩ



Classical Application 3: High and Low Restraint (Band Pass)



C9=0.22uF,R6=NC,C8=NC,R5=18kΩ,C10=NC,R3=NC,R4=33kΩ





Absolute Maximum Ratings

VIN to GND	-----	-0.3V to 6.0V
VDD to GND	-----	-0.3V to 6.5V
Other pin to GND	-----	-0.3V to 6.5V
Lead Temperature (Soldering, 10 sec.)	-----	260°C
Storage Temperature Range	-----	-65°C to 165°C
Operation Junction Temperature Range	-----	-40°C to 125°C
Operation Ambient Temperature Range	-----	-40°C to 85°C
Maximum Junction Temperature Range	-----	150°C
Maximum Power Dissipation (PD,TA<40°C)	-----	2.6W
Thermal resistance (junction to ambient)	-----	56°C/W

Electrical Characteristics For Amplifier

(VDD = 5V, RL=4Ω , TA = 25° C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ		Max	Units
				Class-D	Class-AB		
Audio							
Supply power	VDD		2.5			6.0	V
Output power	Po	THD+N=10%, f=1kHz,RL=4Ω	VDD=6.0V	4.8	4.7		W
			VDD=5.0V	3.2	3.2		
		THD+N=10%, f=1kHz,RL=3Ω	VDD=6.0V	6.0	5.9		
			VDD=5.0V	3.8	3.7		
		THD+N=10%, f=1kHz,RL=2Ω	VDD=6.0V	8.0	7.9		
			VDD=5.0V	5	5		
		THD+N=1%, f=1kHz,RL=4Ω	VDD=6.0V	3.8	3.7		
			VDD=5.0V	2.5	2.6		
THD+N=1%, f=1kHz,RL=3Ω	VDD=6.0V	4.8	4.7				
	VDD=5.0V	3.1	3.2				
THD+N=1%, f=1kHz,RL=2Ω	VDD=6.0V	6.1	6.0				
	VDD=5.0V	4	4				
Power supply ripple rejection	PSRR	INPUT ac-grounded with CIN=0.47uF,	f=100HZ	75			dB
			f=1KHz	50			
Signal-to-noise ratio	SNR	VDD=5V,Class_AB	f=1KHz	91			dB
		VDD=5V,Class_D	f=1KHz	90			
Output noise	VN	INPUT ac-grounded		100			μV
Efficiency	η	RL=4Ω, Po=3.2W	f=1KHz	84			%
VOS		VDD=5.0V, VSD =0V		1.1	2.5		mV

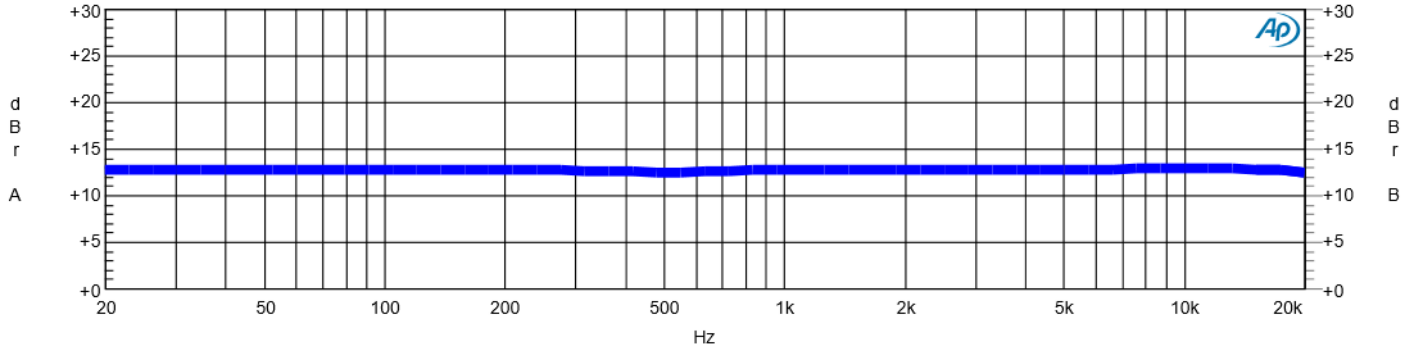


Threshold voltage of class D	VMOD_D	VDD=2.5-6.0V		75%VDD			V
Threshold voltage of class AB	VMOD_AB	VDD=2.5-6.0V				50%VDD	V
Threshold voltage of shutdown pin	VSD_H	VDD=2.5-6.0V		1.4			V
	VSD_L	VDD=2.5-6.0V				0.4	V
Shutdown current	ILEAK	VSD =VDD=5.0V			2		uA
Quiescent current	IQ	VDD=5.0V	No load		4.65	7	mA
Frequency for class_D	fsw				500		kHz
BOOST							
Supply Voltage	V _{IN}			2.2		5.5	V
Output Voltage Range	V _{OUT}			2.5		6.5	V
Supply Current(Shutdown)	I _{SD}	VEN=VOUT=0V, VIN=5V				1	uA
Supply Current	I _{IN}	VEN=VIN=3.6V, VFB=0.62V				150	uA
Feedback Voltage	V _{FB}			0.588	0.6	0.612	V
Feedback Input Current	I _{FB}	VFB=0.6V				50	nA
Switching Frequency	F _{SW}				1200		kHz
Maximum Duty Cycle	F-Duty				90		%
EN Input Low Voltage	V _{EN-OFF}					0.4	V
EN Input High Voltage	V _{EN-ON}			1.4			V
Limit current of power MOSFET	I _{LIMIT}				6		A
RDS(ON)	R _{DS(ON)}	VOUT=3.3V			100		mΩ



Typical Operating Characteristic For Amplifier

Audio Precision



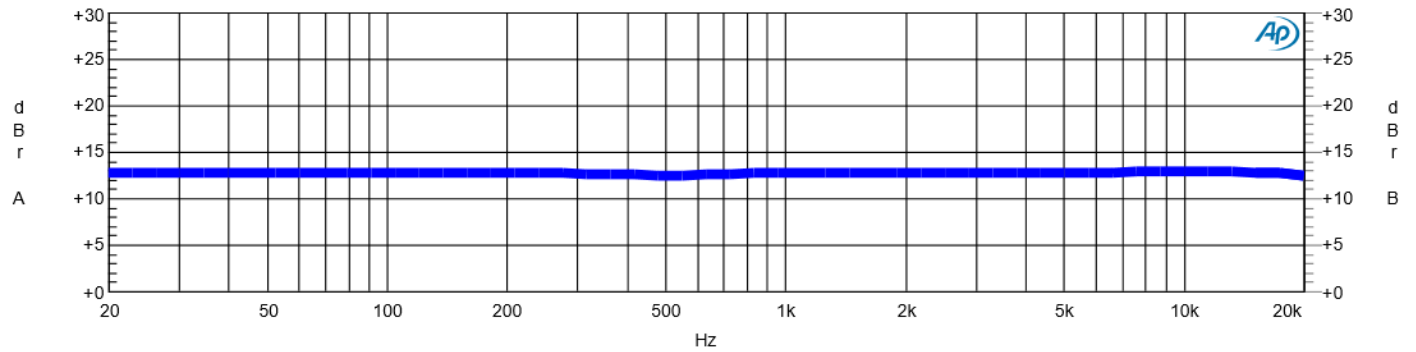
Sweep	Trace	Color	Line Style	Thick	Data	Axis	Comment
1	1	Cyan	Solid	1	Analyzer.Level A	Left	
1	2	Blue	Solid	7	Analyzer.Level B	Right	

Rapid (<2 seconds) frequency response measurement.
 Can be even faster if the lowest frequencies are not included.
 Press F4 to set the 1kHz dBr A and dBr B reference.
 Optimize for a detailed view.

A-A FREQ RESP FAST @ 4ohm PO=4.8W CLASS AB VDD=6V.ats2



Audio Precision



Sweep	Trace	Color	Line Style	Thick	Data	Axis	Comment
1	1	Cyan	Solid	1	Analyzer.Level A	Left	
1	2	Blue	Solid	7	Analyzer.Level B	Right	

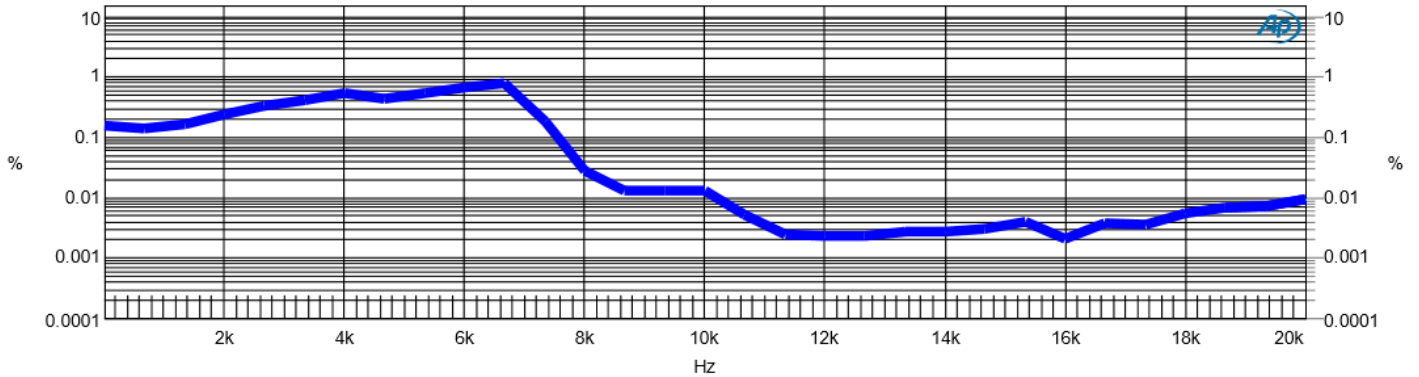
Rapid (<2 seconds) frequency response measurement.
 Can be even faster if the lowest frequencies are not included.
 Press F4 to set the 1kHz dBr A and dBr B reference.
 Optimize for a detailed view.

A-A FREQ RESP FAST @ 4ohm PO=4.8W CLASS D VDD=6V.ats2



Audio Precision

A-A THD+N vs FREQUENCY



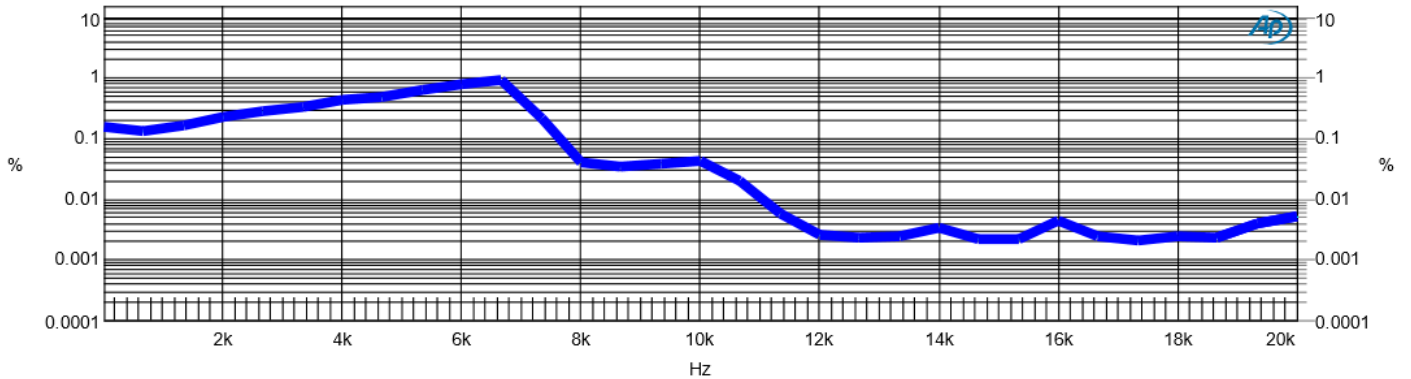
Sweep	Trace	Color	Line Style	Thick	Data	Axis	Comment
1	1	Cyan	Solid	1	Analyzer.TH+N Ratio B	Left	
1	2	Blue	Solid	7	Analyzer.TH+N Ratio B	Right	

A single sweeps produces a stereo THD+N sweep of Ch A and Ch B when data 1 is set for THD+N and the Stereo box is checked. The upper Analyzer bandwidth is 20kHz. At a 6kHz fundamental only the 2nd and 3rd harmonics are included, above 10kHz only the noise is included in the measurement bandwidth. For band-limited systems IMD testing is better.

A-A THD+N VS FREQ @4ohm PO=3W CLASS AB VDD=6V.ats2

Audio Precision

A-A THD+N vs FREQUENCY



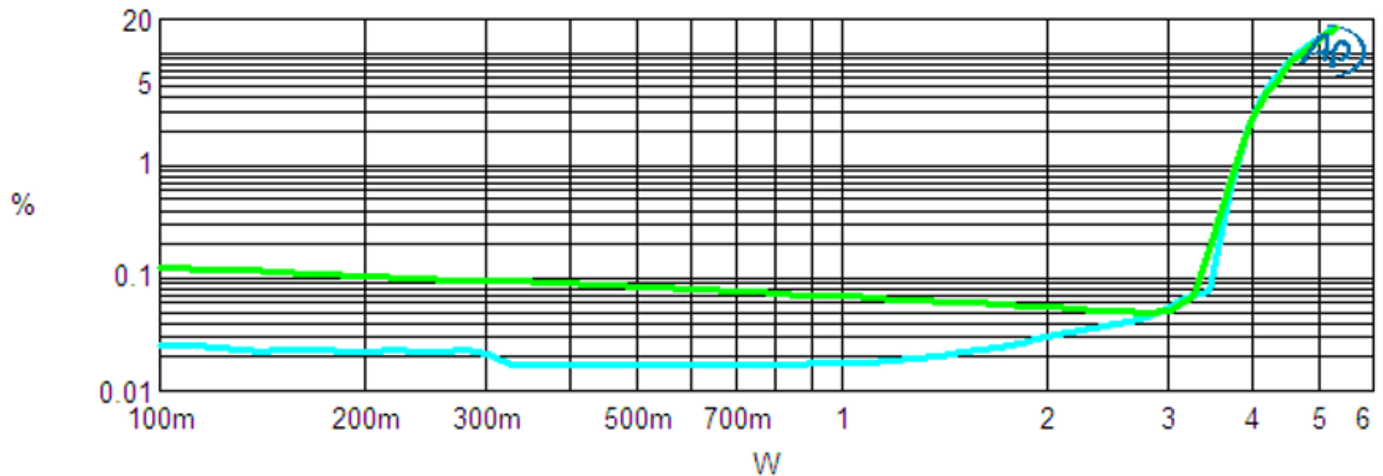
Sweep	Trace	Color	Line Style	Thick	Data	Axis	Comment
1	1	Cyan	Solid	1	Analyzer.TH+N Ratio B	Left	
1	2	Blue	Solid	7	Analyzer.TH+N Ratio B	Right	

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A-A THD+N VS FREQ @4ohm PO=3W CLASS D VDD=6V.ats2

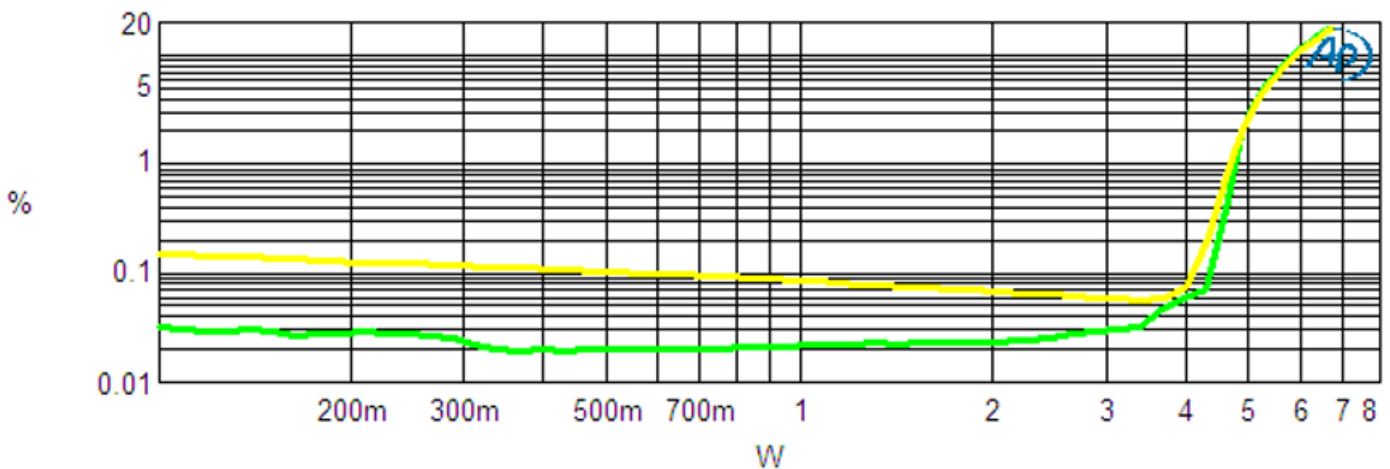


Audio Precision



Sweep	Trace	Color	Line Style	Thick	Data	Axis	Comment
1	1	Cyan	Solid	3	Analyzer.THD+N Ratio A	Left	6V 40ohm Class D
2	1	Green	Solid	3	Analyzer.THD+N Ratio A	Left	6V 40ohm Class AB

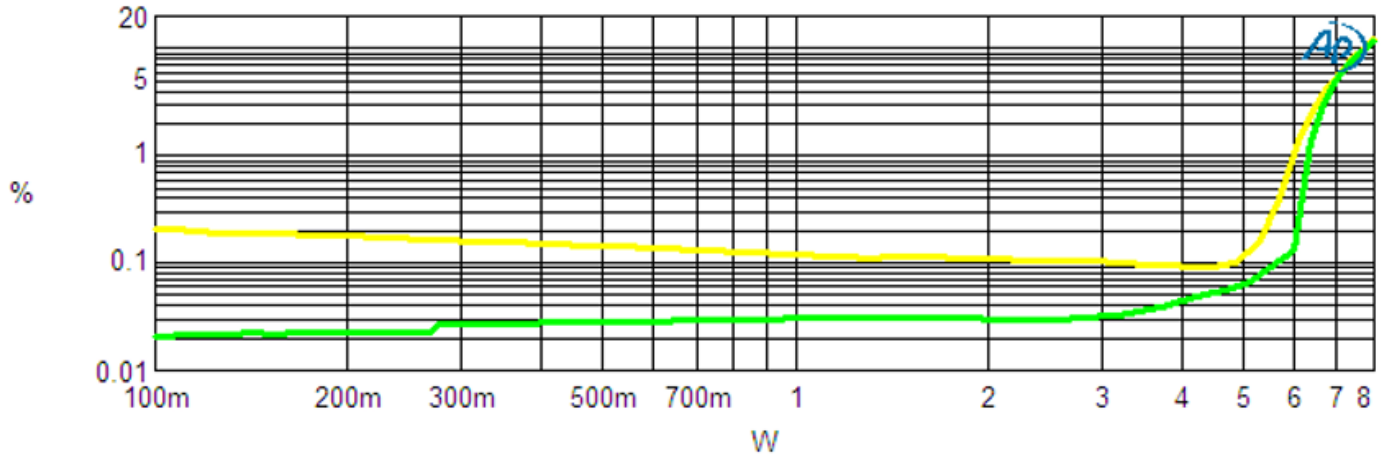
Audio Precision



Sweep	Trace	Color	Line Style	Thick	Data	Axis	Comment
1	1	Green	Solid	3	Analyzer.THD+N Ratio A	Left	6V 30ohm Class D
2	1	Yellow	Solid	3	Analyzer.THD+N Ratio A	Left	6V 30ohm Class AB



Audio Precision

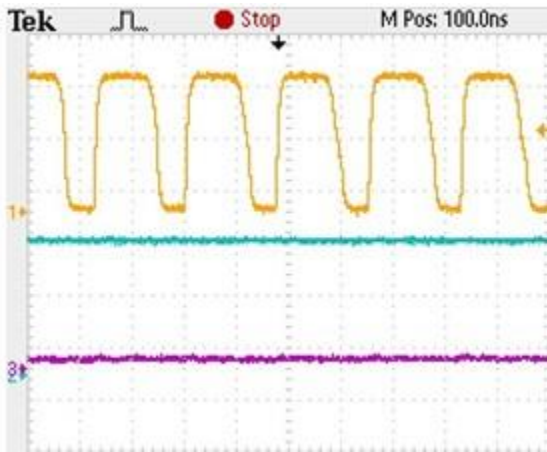


Sweep	Trace	Color	Line Style	Thick	Data	Axis	Comment
1	1	Green	Solid	3	Analyzer.THD+N Ratio A	Left	6V 2ohm Class D
2	1	Yellow	Solid	3	Analyzer.THD+N Ratio A	Left	6V 2ohm Class AB

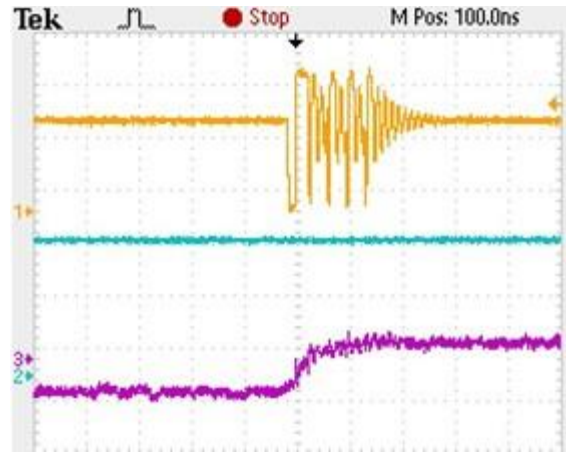




Typical Operating Characteristic For Boost Convertor



Vin=3.3V Vout=5V, 0mA



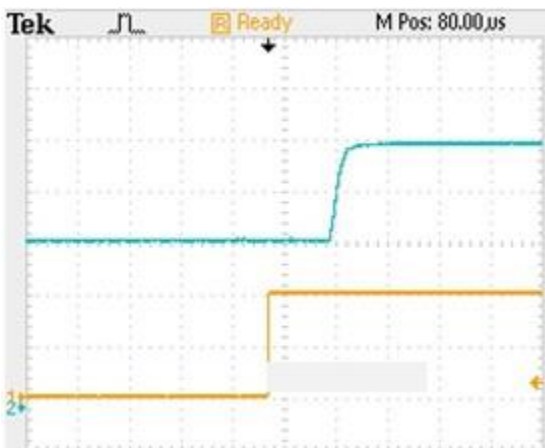
Vin=3.3V Vout=5V, 50mA



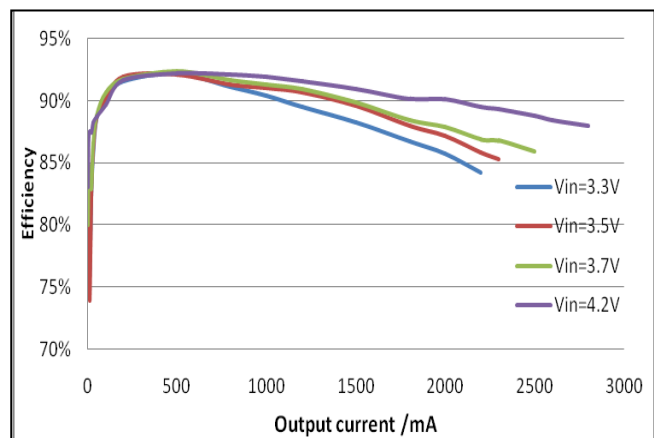
Vin=3.3V Vout=5V, 100mA



Vin=3.3V Vout=5V, 2A



Start up wave



Efficiency VS. Output current



Applications Information

Maximum Gain

The LPA2163 has two internal amplifier stages. The first stage's gain is externally configurable, while the second stage's is internally fixed. The closed-loop gain of the first stage is set by selecting the ratio of R4 to R5 while the second stage's gain is fixed at 1.5x. The output of amplifier serves as the input to amplifier 2, thus the two amplifiers produce signals identical in magnitude, but different in phase by 180°. Consequently, the differential gain for the IC is: $A_v = 2 * 1.5 * R_4 / R_5$ (for class_AB & class_D)

Shutdown operation

In order to reduce power consumption while not in use, the LPA2163 contains shutdown circuitry to turn off the amplifier's bias circuitry. This shutdown feature turns the amplifier off when logic high is applied to the SD pin. By switching the SD pin connected to high voltage, the LPA2163 supply current draw will be minimized in idle mode.

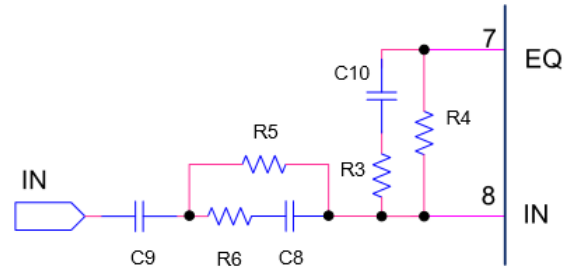
Power supply decoupling

The LPA2163 is a high performance CMOS audio amplifier that requires adequate power supply decoupling to ensure the output THD and PSRR a low as possible. Power supply decoupling affects low frequency response. Optimum decoupling is achieved by using two capacitors of different types targeting to different types of noise on the power supply leads. For higher frequency transients, spikes, or digital hash on the line, a good low equivalent-series-resistance (ESR) ceramic capacitor, typically 1.0µF, works best, placing it as close as possible to the device VDD terminal. For filtering lower- frequency noise signals, a large capacitor of 20µF (ceramic) or greater is recommended, placing it near the audio power amplifier.

Signal Frequency suppress

The LPA2163 has a EQ pin which is the negative output of amplifier as show below. With R3 and C10, we can suppress high frequency part of signal. And the low frequency part of signal could be attenuated by R6 and C8.

$$f_H = \frac{1}{2\pi R_6 C_8}; \quad f_L = \frac{1}{2\pi R_3 C_{10}}$$



Over Temperature Protection

Thermal protection on the LPA2163 prevents the device from damage when the internal die temperature exceeds 150°C. Once the die temperature exceeds the thermal set point, the device outputs are disabled. This is not a latched fault. The thermal fault is cleared once the temperature of the die is reduced by 30°C. This large hysteresis will prevent motor boating sound well and the device begins normal operation at this point without external system intervention.

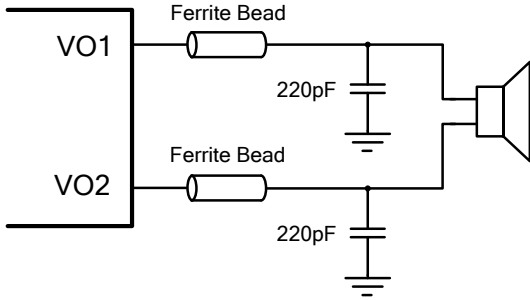
Analog Reference Bypass Capacitor (CBYP)

In addition to system cost and size, click and pop performance is affected by the size of the input coupling capacitor, CBYP. A larger input coupling capacitor requires more charge to reach its quiescent DC voltage (nominally 1/2 VDD). This charge comes from the internal circuit via the feedback and is apt to create pops upon device enable. Thus, by minimizing the capacitor size based on necessary low frequency response, turn-on pops can be minimized.

The Analog Reference Bypass Capacitor (CBYP) is the most critical capacitor and serves several important functions. During start-up or recovery from shutdown mode, CBYP determines the rate at which the amplifier starts up. The second function is to reduce noise caused by the power supply coupling into the output drive signal. This noise is from the internal analog reference to the amplifier, which appears as degraded PSRR and THD+N.

How to reduce EMI

A simple solution is to put an additional capacitor 220pF at power supply terminal for power line. The traces from amplifier to speakers should design as short as we can.



Applications Information(for Boost)

The Boost a 1200KHz fixed frequency, current-mode regulation architecture to regulate the boost convertor output voltage. the output voltage through an external resistive voltage divider and compares that to the internal 0.6V reference to generate the error voltage to the inductor current to regulate the output voltage. The use of current-mode regulation improves transient response and control loop stability.

When the boost convertor is disabled (EN=Low), both power switches are off. There is no current path from SW to OUT. Therefore, the output voltage discharges to ground. When the boost convertor is enabled (EN=High), a limited start-current charges the output voltage rising to SW, then TH part operates in force PWM mode for regulating the output voltage to the target value. At the beginning of each cycle, the N-channel MOSFET switch is turned on, forcing the inductor

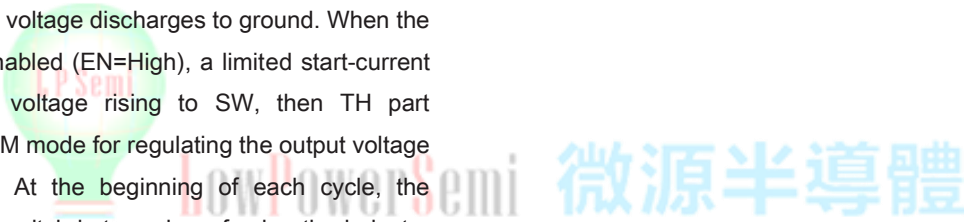
current to rise. The current at the source of the switch is internally measured and converted to a voltage by the current sense amplifier. That voltage is compared to the error voltage. When the inductor current rises sufficiently, the PWM comparator turns off the switch, forcing the inductor current to the output capacitor which forces the inductor current to decrease. The peak inductor current is controlled by the error voltage. Thus the output voltage controls the inductor current to satisfy the lode.

Setting the Output Voltage

Set the output voltage by selecting the resistive voltage divider ratio. The voltage divider drops the output voltage to the 0.6V feedback voltage. Use a 100K resistor for R2 of the voltage divider. Determine the high-side resistor R1 by the equation:

$$V_{out} = (R1/R2 + 1) \times V_{FB}$$

$$V_{out} = (R1/R2 + 1) \times 0.6V$$

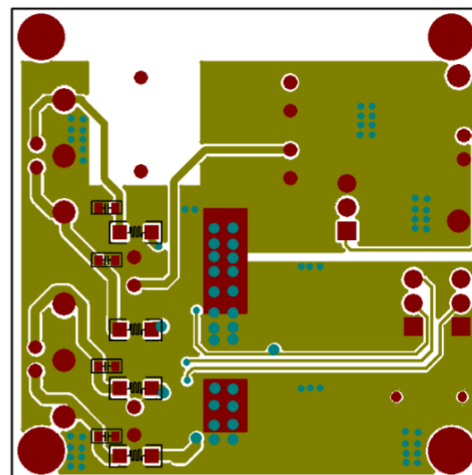
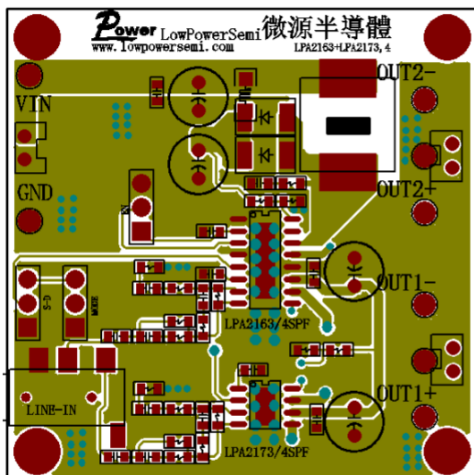




PCB Layout notices

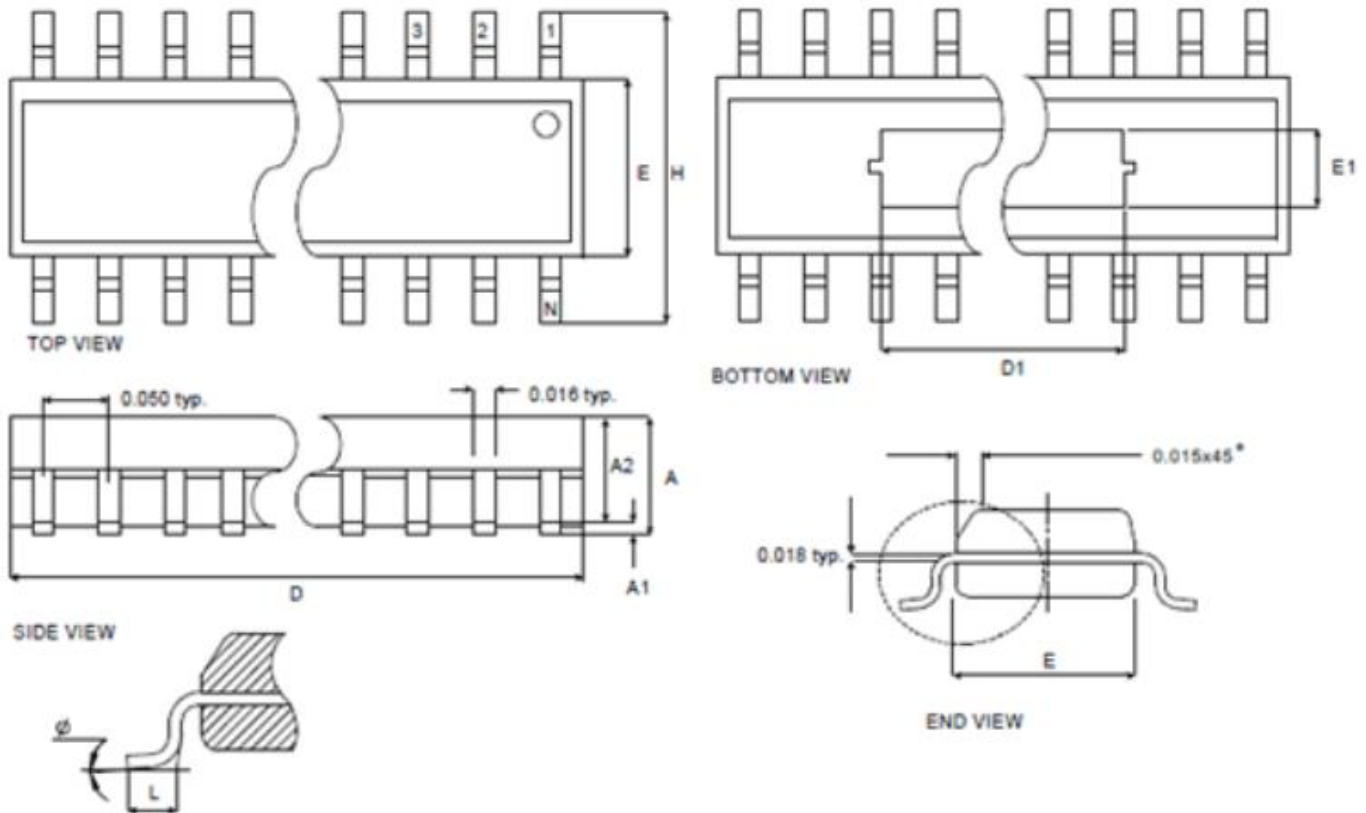
- 1, In the path of the power supply, plus a 1uF and a 10uF to ground high-frequency filter capacitor. These caps can be connected to the thermal pad directly for an excellent ground connection. Consider adding a small, good quality low ESR ceramic capacitor may achieve better sound effects.
- 2, Large (470 μF or greater) bulk power supply decoupling capacitors should be placed near the LPA2163 on the VDD supplies. Local, high-frequency bypass capacitors should be placed as close to the VDD pins as possible.
- 3, The power line, ground line and filter capacitor and bypass capacitors as close to the chip's pins, remember not to put the capacitor on the back of the board, through tiny holes through the jumper even over. Keep the current loop from each of the outputs through the ferrite bead and the small filter cap and back to PGND as small and tight as possible. The size of this current loop determines its effectiveness as an antenna.
- 4, Power, ground, and a large current line must try to be wide enough, if you want to add vias, the number of through-holes must be at least 6. The thermal pad must be soldered to the PCB for proper thermal performance and optimal reliability.
- 5, GND and VDD should be put independently, high-power signals to avoid interference.
- 6, If you want to pursue as large as the effect of power, a large selection of speakers or sound chamber with low resistance (such as 3.6Ω) speakers, or added to improve the supply voltage boost circuit.
- 7, Including the line between large current cell and chip, the inductor should be as close and short as possible to chip for a high performance. Adding a coil to this pin would be helpful for EMI certification. If there is a high standards needed in LPA2163 application, we could add a coil and capacitor between chip and speaker constituting a LC filter which coil would be 100MHZ, 100~150Ω and its DCI beyond 3A placing as close as possible to chip, the capacitor should be 1nF connecting the PGND.
- 8, The position under the amplifier chip on the board must be added vents and large areas of exposed copper and tin to enhance heat dissipation.
- 9, In case of fixed gain and meeting demand, it should make CIN small as possible as we can because it constitute a high through filter with Rin which cutoff frequency is $1/2 * 3.414 * C_{in} * R_{in}$. A high capacitance cap could make POP worse.

PCB LAYOUT (LPA2163SPF+LPA2173SPF)





Packaging Information



Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
D	9.80	10.0	0.386	0.394
D1	4.115 REF		0.162 REF	
E	3.81	3.99	0.150	0.157
E1	2.184 REF		0.086 REF	
H	5.79	6.20	0.228	0.244
L	0.41	1.27	0.016	0.050
ϕ	0°	8°	0°	8°